

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16130
1.3 Title of PCN	STM32U375x and STM32U385x - product enhancement
1.4 Product Category	STM32U375x and STM32U385x
1.5 Issue date	2026-08-31

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	TSMC (Taiwan)

4. Description of change

	Old	New
4.1 Description	STM32U3 - (revision Y) product shows some limitations : - Retained SRAMs might be corrupted after Stop 1 mode or after reset. - LSE in bypass mode may not be functional. - Over-consumption from VDD when VDDA is lower than VDD. - TSC is partially not functional on PA15 and PB15. - Invalid DAC output voltage by DAC kernel clock setting. as described in Errata Sheet ES0626 - Rev 2.1 – February 2026	STM32U3 - (revision X) product enhancement fixes and limitations as listed below: - Retained SRAMs might be corrupted after Stop 1 mode or after reset - fixed. - LSE in bypass mode may not be functional - fixed - LSE bypass mode allowed only digital input - new limitation - Over-consumption from VDD when VDDA is lower than VDD- fixed. - TSC is partially not functional on PA15 and PB15 - fixed. - Invalid DAC output voltage by DAC kernel clock setting - fixed. - SRAM1PD and SRAM2PD bits of PWR_CR1 can't be used to power down SRAMs – new limitation. - Key wrap and SFI RSS features may not be functional in specific environmental conditions - fixed As described in Errata Sheet ES0626 - Rev 3 – July 2026
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Current STM32U375x and STM32U385x (Revision Y) product has limitations described in Errata Sheet ES0626	

5. Reason / motivation for change

5.1 Motivation	Improvements was implemented to increase robustness, performances and quality of our products.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Traceability ensured by ST internal tools. Die revision changes from "Y" to "X" on Package Marking.
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7. Timing / schedule	
7.1 Date of qualification results	2026-10-20
7.2 Intended start of delivery	2026-11-18
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	16130 MDRF-GPAM RER2206 - PCN16130 STM32U375x STM32U385x - Die 454_X cut1.3 - Rel plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-08-31

9. Attachments (additional documentations)
16130 Public product.pdf 16130 MDRF-GPAM RER2206 - PCN16130 STM32U375x STM32U385x - Die 454_X cut1.3 - Rel plan.pdf 16130 _Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32U375CGT6Q	
	STM32U375CGU6Q	
	STM32U375CGY6QTR	
	STM32U375KGU6	
	STM32U375KGU7	
	STM32U375RGI6Q	
	STM32U375RGT6Q	
	STM32U375RGY6QTR	
	STM32U375VGT6Q	
	STM32U385CGT6	
	STM32U385CGT6Q	
	STM32U385CGU6	
	STM32U385CGU6Q	
	STM32U385CGY6QTR	
	STM32U385KGU6	
	STM32U385RGI6	
	STM32U385RGI6Q	
	STM32U385RGT6	
	STM32U385RGT6Q	
	STM32U385RGY6QTR	
	STM32U385VGI6	
	STM32U385VGI6Q	
	STM32U385VGT6	
	STM32U385VGT6Q	

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